The 7th International Congress on



3D Materials Science 2025

CALL FOR ABSTRACTS EXTENDED SUBMISSION DEADLINE: DECEMBER 13, 2024

The 7th International Congress on 3D Materials Science (3DMS 2025) is the premier forum for presentations of current interest and significance to the three-dimensional (3D) characterization, visualization, quantitative analysis, modeling, and development of structure–property relationships of materials, as well as big data and machine learning issues associated with 3D materials science. This congress will provide an intimate environment for rich discussions and interactions among the key researchers in the world to not only assess the state-of-the-art within the various elements of 3D materials science, but also to road map the key areas of future research.

3DMS 2025 will include the following specific technical topics:

- · 3D Characterization and Modeling in Advanced Manufacturing
- 3D Characterization and Modeling in Sustainable and Energy Materials
- 3D Data Processing, Software, and Reconstruction Algorithms
- 3D Imaging at the Nano-Scale
- Artificial Intelligence Methods for 3D Data Analysis
- Automated and Autonomous 3D Materials Research
- Emerging 3D Characterization Techniques and Instrumentation
- Industrial Applications of 3DMS
- Methods of Materials Simulation and Modelling in 3D & 4D
- Multimodal, Multiscale, and/or Correlative 3D Characterization
- Process-Microstructure-Property Relationships in 3D
- Time Resolved 3D Characterization (i.e., 4D experiments)

Congress participants are encouraged to submit their work to the TMS journal *Integrating Materials and Manufacturing Innovation*, which will be publishing a topical collection dedicated to this event. This collection will take the place of a traditional conference proceedings publication. Only submissions from participants will be considered for this collection. Submissions will go through the journal's standard peer review process, and there is no guarantee of acceptance.The journal submission deadline is August 31, 2025.

Submit your abstract at www.tms.org/3DMS2025



JUNE 15-19, 2025 Anaheim Marriott Anaheim, California, USA







8 TH WORLD CONGRESS ON INTEGRATED COMPUTATIONAL MATERIALS ENGINEERING (ICME 2025)

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